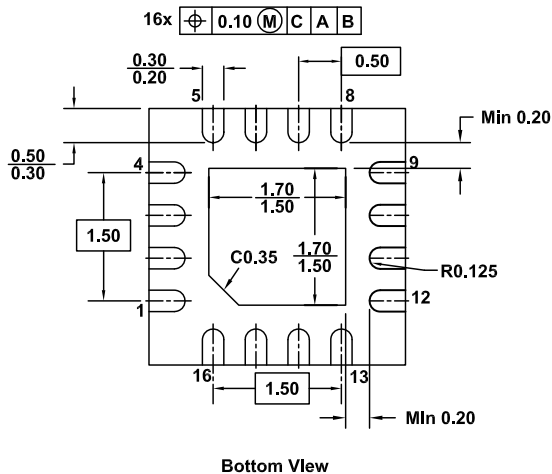
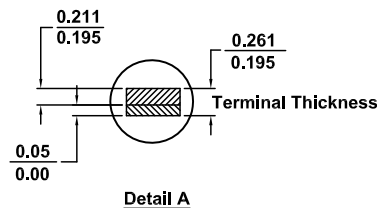
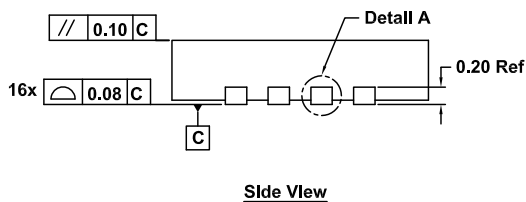
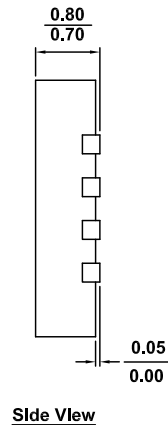
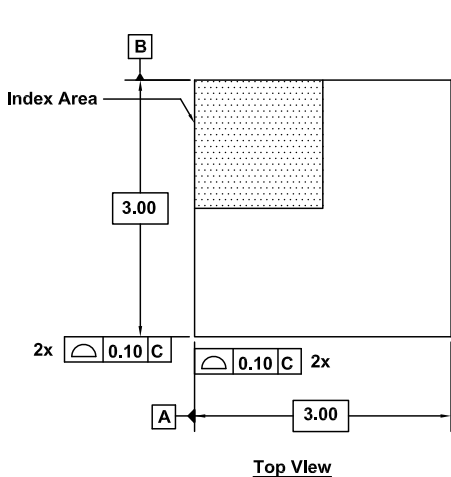


Plastic Packages for Integrated Circuits

Package Outline Drawing

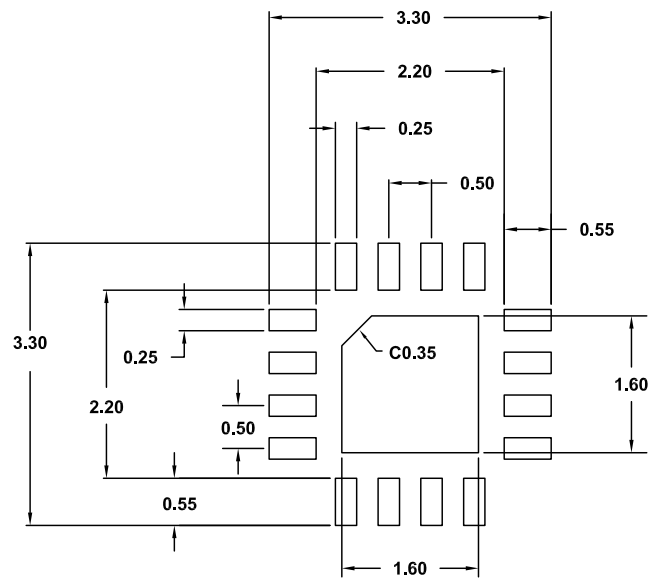
L16.3x3F
 16 Lead Thin Quad Flat No-Lead Package
 Rev 0, 2/20



Notes :

1. All dimensions are in mm. Angles are in degrees.
2. Coplanarity applies to the exposed pad and the terminals.
Coplanarity shall not exceed 0.05mm.
3. Warpage shall not exceed 0.05mm.
4. The package length and package width are considered as special characteristics.
5. See JEDEC MO-220.

Plastic Packages for Integrated Circuits



Recommended Land Pattern Dimension

Notes:

1. All dimensions are in mm. Angles are in degrees.
2. Top down view. As viewed on PCB.
3. Land pattern recommendation per IPC-7351B generic requirement for surface mount design and land pattern.